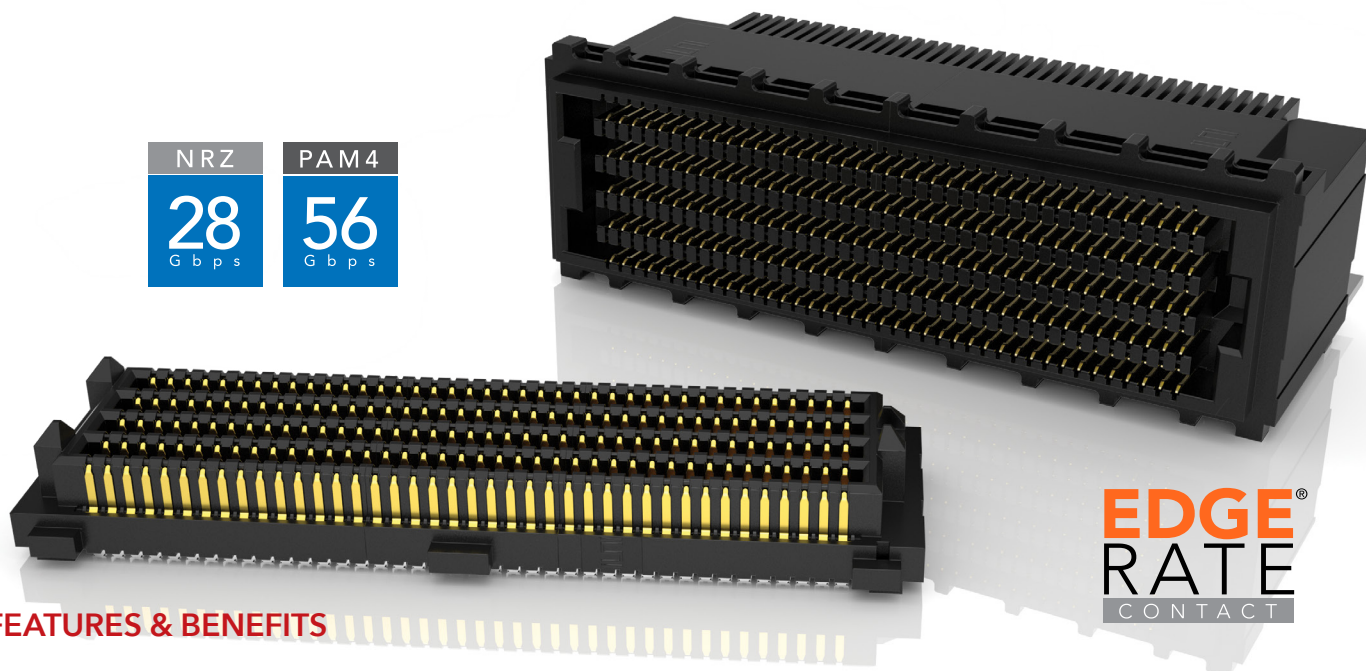
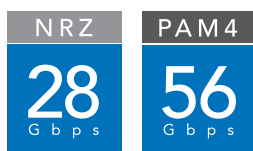


# SEARAY<sup>TM</sup>.8mm

## ULTRA HIGH-DENSITY, HIGH-SPEED OPEN-PIN-FIELD ARRAYS

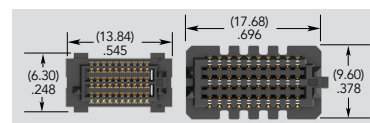
(0.80 mm) .0315" PITCH



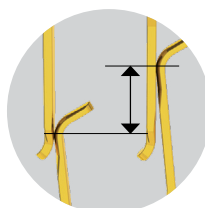
**EDGE**  
**RATE**  
CONTACT

### FEATURES & BENEFITS

- 0.80 mm (.0315") pitch grid
- 50% board space savings versus .050" (1.27 mm) pitch arrays
- Performance up to 28 Gbps NRZ/56 Gbps PAM4
- Rugged Edge Rate<sup>®</sup> contact system
- Up to 500 I/Os
- 7 mm and 10 mm stack heights
- Solder charge terminations for ease of processing
- Lower insertion/withdrawal forces
- Analog over Array<sup>™</sup> capable
- Severe Environment Testing qualified (SEAM8/SEAF8); aligns with MIL-DTL-55302. Visit [samtec.com/set](http://samtec.com/set)

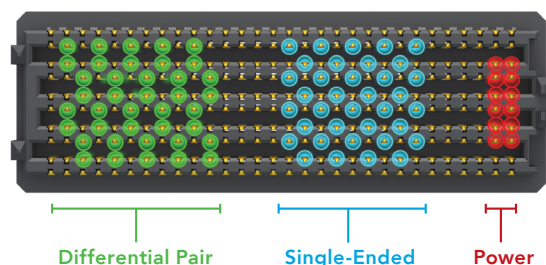


0.80 mm pitch vs. 1.27 mm pitch  
(60 pins shown)



(0.95 mm) .037"  
Nominal Wipe

### MAXIMUM GROUNDING & ROUTING FLEXIBILITY



### KEY SPECIFICATIONS (SEAF8/SEAM8)

SERIES	INSULATOR MATERIAL	CONTACT MATERIAL	PLATING	OPERATING TEMP RANGE	CURRENT RATING	VOLTAGE RATING	LEAD-FREE SOLDERABLE
SEAM8	Black LCP	Copper Alloy	Au or Sn over 50 μ" (1.27 μm) Ni	-55 °C to +125 °C	1.3 A per pin (10 adjacent pins powered)	220 VAC/311 VDC	Yes
SEAF8					1.1 A per pin (10 adjacent pins powered)	240 VAC/339 VDC	
SEAF8-RA							

# (0.80 mm) .0315" PITCH • ULTRA HIGH-DENSITY ARRAYS

SERIES	NO. PINS PER ROW	LEAD STYLE	PLATING OPTION	NO. OF ROWS	SOLDER TYPE	OPTION	"X"R
SEAM8 Terminal	-10, -20, -30, -40, -50	-S02.0 = 2 mm Body Height (SEAM8 only)	-L = 10 μ" (0.25 μm) Gold on contact area, Matte Tin on solder tail	-04 -06 -08 -10	-3 = Lead-Free Solder Crimp	-GP = Guide Post (-S02.0 lead style only) (Mates with SEAF8-RA-GP)	Tape & Reel is standard. Leave blank for Tape & Reel.
SEAF8 Socket		-S05.0 = 5 mm Body Height (SEAM8 only)					-FR = Full Reel Tape & Reel (must order max. quantity per reel; contact Samtec for quantity breaks)
		-05.0 = 5 mm Body Height (SEAF8 only)					

**SEAM8**  
Board Mates:  
SEAF8  
Cable Mates:  
ESCA  
Standoffs:  
JSO

NO. OF ROWS	A
-04	(4.30) .169
-06	(6.30) .248
-08	(8.30) .327
-10	(10.30) .406

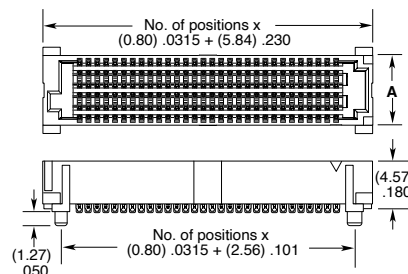
LEAD STYLE	B
-S02.0	(4.54) .179
-S05.0	(7.54) .297

View complete specifications at: [samtec.com?SEAM8](http://samtec.com?SEAM8)

**ALSO AVAILABLE**  
Contact Samtec

Other platings  
Tin/Lead solder crimps

SEAF8	Board Mates: SEAM8 Cable Mates: ESCA Standoffs: JSO
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MATED HEIGHTS*		
SEAF8 LEAD STYLE	SEAM8 LEAD STYLE	
	-S02.0	-S05.0
-05.0	(7.00) .276	(10.00) .394

\*Processing conditions will affect mated height.

**Notes:**  
Polyimide Pick & Place Pad standard without specifying -K.

Severe Environment Testing qualified; aligns with MIL-DTL-55302. Visit [samtec.com/set](http://samtec.com/set)

View complete specifications at: [samtec.com?SEAF8](http://samtec.com?SEAF8)

SEAF8	NO. PINS PER ROW	1	PLATING OPTION	NO. OF ROWS	SOLDER TYPE	RA	OPTION	"X"R
	-20, -30, -40, -50		-S = 30 μ" (0.76 μm) Gold on contact area, Matte Tin on solder tail	-04 (-50 positions only) -08 -10	-2 = Lead-Free Solder Crimp		-GP = Guide Post Holes	Tape & Reel is standard. Leave blank for Tape & Reel.
SEAF8-RA (Right-angle)								-FR = Full Reel Tape & Reel (must order max. quantity per reel; contact Samtec for quantity breaks)
Board Mates: SEAM8 Cable Mates: ESCA								

NO. OF ROWS	A	B
-04	(12.48) .491	(7.46) .294
-08	(16.48) .649	(11.46) .451
-10	(18.48) .728	(13.46) .530

NO. PINS PER ROW	C	D
-20	(29.62) 1.166	(24.12) .950
-30	(37.62) 1.481	(32.12) 1.265
-40	(45.62) 1.796	(40.12) 1.580
-50	(53.62) 2.111	(48.12) 1.894

**Notes:**  
Some sizes, styles and options are non-standard, non-returnable

View complete specifications at: [samtec.com?SEAF8-RA](http://samtec.com?SEAF8-RA)